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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	12 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	52
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064lc68-12yy

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The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			√ (1)
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface (2)	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:

- (1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
- (2) The MultiVolt I/O interface is not available in 44-pin packages.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram

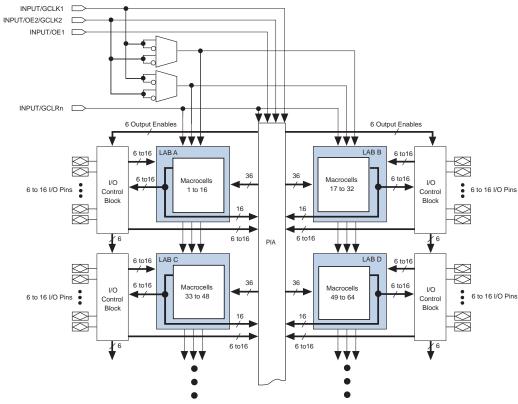


Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

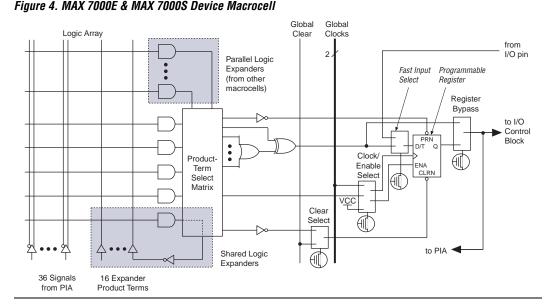


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

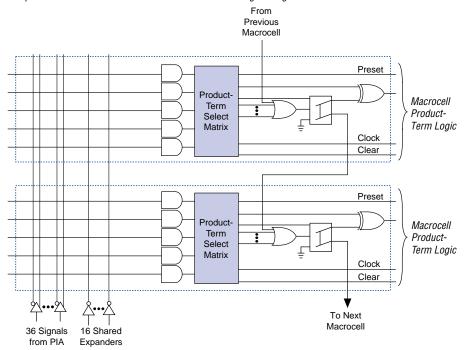
For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

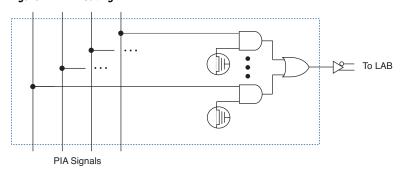
Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



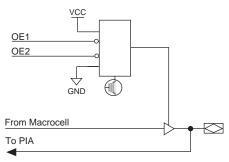
While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

I/O Control Blocks

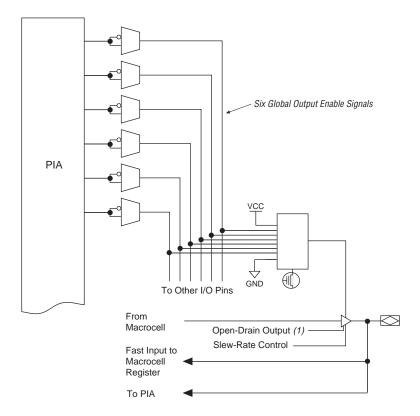
The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC}. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices



MAX 7000E & MAX 7000S Devices



Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , t_{ACL} , and t_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V $V_{\rm CCINT}$ level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When $V_{\rm CCIO}$ is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with $V_{\rm CCIO}$ levels lower than 4.75 V incur a nominally greater timing delay of $t_{\rm OD2}$ instead of $t_{\rm OD1}$.

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

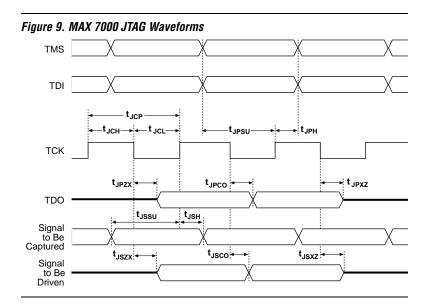


Figure 9 shows the timing requirements for the JTAG signals.

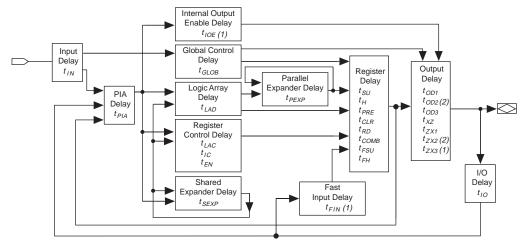
Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (*IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*).

Figure 12. MAX 7000 Timing Model



Notes:

- (1) Only available in MAX 7000E and MAX 7000S devices.
- Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.



For more infomration, see *Application Note* 94 (Understanding MAX 7000 *Timing*).

Table 2	5. MAX 7000 & MAX 7000E	External Timing I	Paramete	ers /	lote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t _{SU}	Global clock setup time		11.0		11.0		12.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t _{CH}	Global clock high time		5.0		6.0		6.0		ns
t _{CL}	Global clock low time		5.0		6.0		6.0		ns
t _{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t _{AH}	Array clock hold time		4.0		4.0		5.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t _{ACH}	Array clock high time		6.0		6.5		8.0		ns
t _{ACL}	Array clock low time		6.0		6.5		8.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t _{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f _{MAX}	Maximum clock frequency	(6)	100		83.3	_	83.3	_	MHz

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Table 2	77. EPM7032\$ External Time	ing Parameter	s (Part	1 of 2) No	ote (1)					
Symbol	Parameter	Conditions	Speed Grade								
			-	5	-	6	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 2	9. EPM7064\$ External Timi	ing Parameters	(Part 2	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions	Speed Grade								
			-5 -6		-	7	-1	10			
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Table 3	O. EPM7064\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions	Speed Grade								
			-	5	-	6	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		3.0		2.0		ns
t _H	Register hold time		1.7		2.0		2.0		3.0		ns

Table 3	3. EPM7160S External Timi	ing Parameters	(Part 2	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade	1			Unit
			-6 -7 -10 -15							5	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 3	4. EPM7160\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	6	-	7	-1	10	-1	15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t _{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t _H	Register hold time		1.6		2.0		3.0		4.0		ns
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns
t _{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns

Table 3	4. EPM7160S Internal Tin	ning Parameters	(Part	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-6 -7 -10 -15							
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

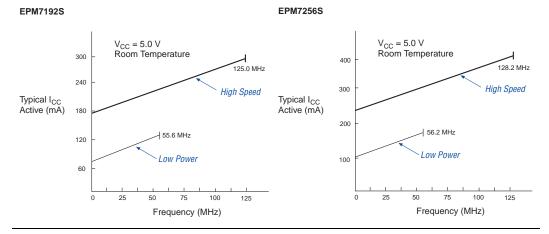
Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2)Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

Tables 37 and 38 show the EPM7256S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade							
Oymboi	i arameter	Conditions		7		-10		-15		
			Min	Max	Min	Max	Min	Max		
		04 05 - 5	IVIIII		IVIIII		IVIIII			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		3.9		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns	
t _{CH}	Global clock high time		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		0.8		2.0		4.0		ns	
t _{AH}	Array clock hold time		1.9		3.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns	
t _{ACH}	Array clock high time		3.0		4.0		6.0		ns	
t _{ACL}	Array clock low time		3.0		4.0		6.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			7.8		10.0		13.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz	
t _{ACNT}	Minimum array clock period			7.8		10.0		13.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz	
f _{MAX}	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz	

Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)



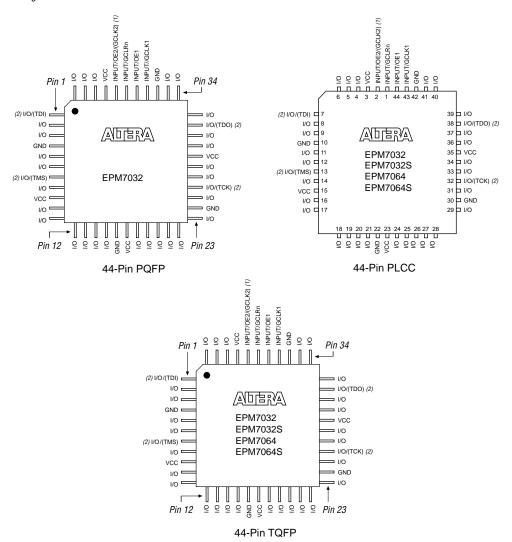
Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.





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